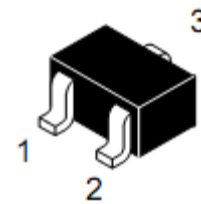
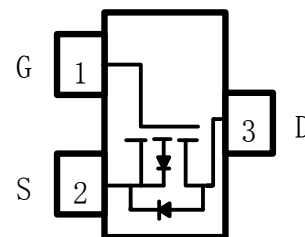


WPM1483
Single P-Channel, -12V, -5A, Power MOSFET
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

V_{DS} (V)	Typical $R_{DS(on)}$ (Ω)
-12	0.031@ $V_{GS} = -4.5V$
	0.040@ $V_{GS} = -2.5V$
	0.056@ $V_{GS} = -1.8V$


SOT-23
Descriptions

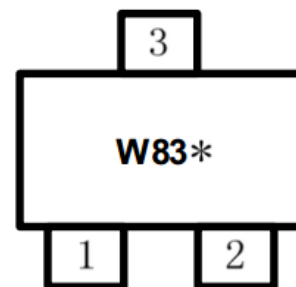
The WPM1483 is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM1483 is Pb-free and Halogen-free.


Pin configuration (Top view)
Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-23

Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging


W=Willsemi
83= Device Code
***= Month (A~Z)**
Marking
Order information

Device	Package	Shipping
WPM1483-3/TR	SOT-23	3000/Reel&Tape

Absolute Maximum ratings

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V_{DS}	-12	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current	I_D	$T_A=25^{\circ}\text{C}$ -5	A
		$T_A=70^{\circ}\text{C}$ -4	
Pulsed Drain Current ^c	I_{DM}	-20	
Maximum Power Dissipation ^b	P_D	$T_A=25^{\circ}\text{C}$ 1.2	W
		$T_A=70^{\circ}\text{C}$ 0.8	
Operating Junction Temperature	T_J	-55 to 150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}\text{C}$

Thermal resistance ratings

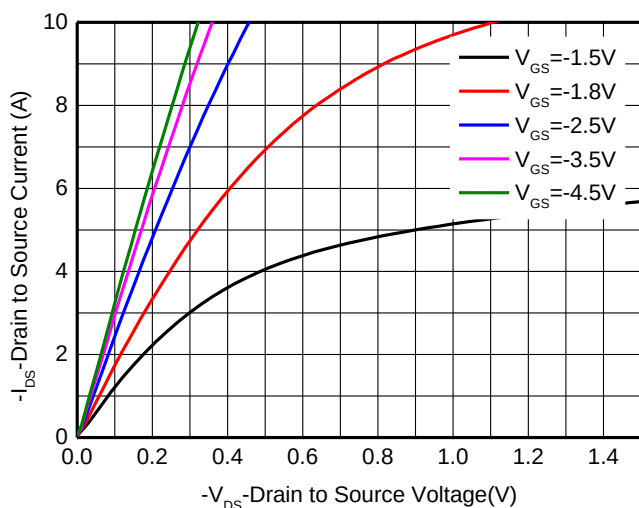
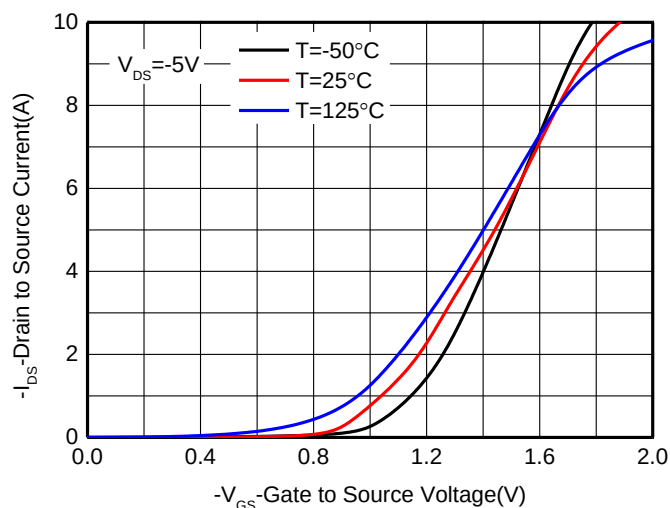
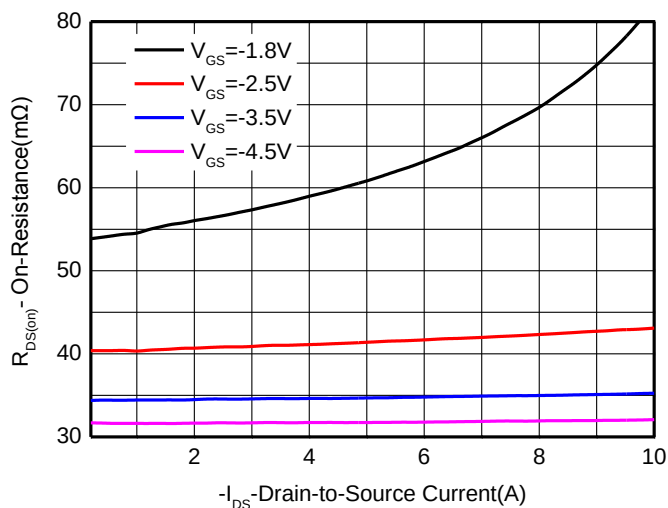
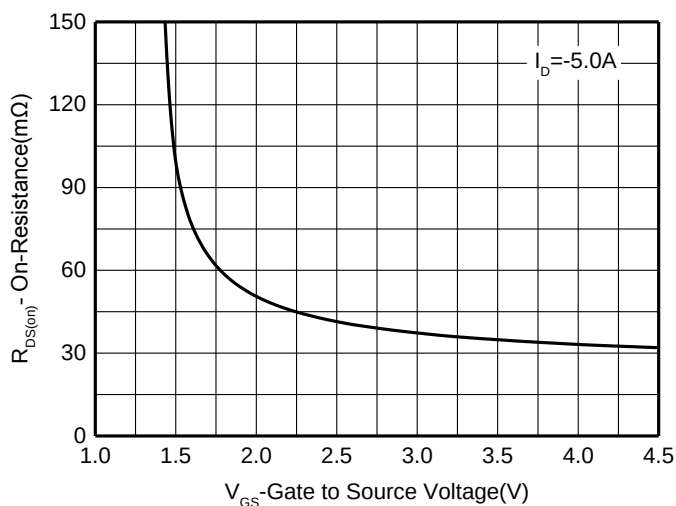
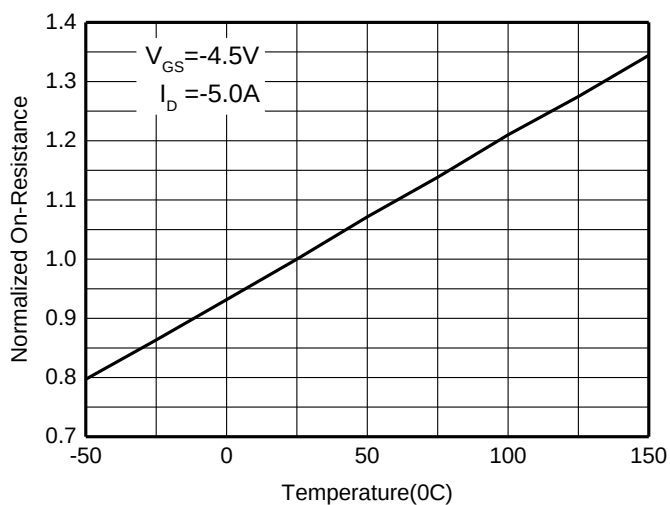
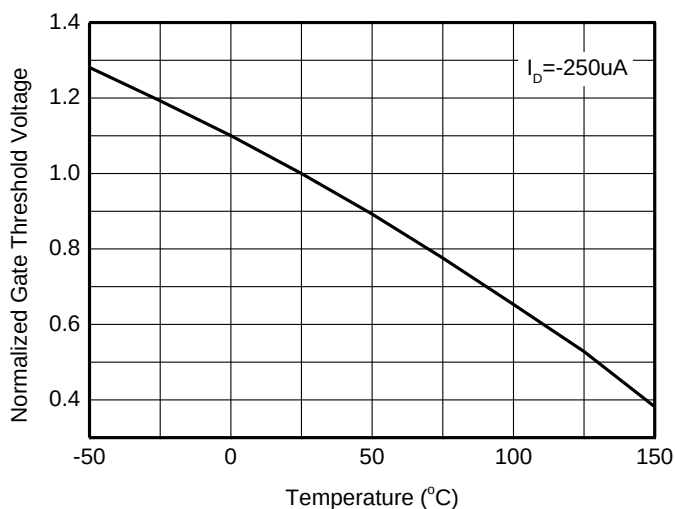
Single Operation					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$t \leq 10\text{ s}$	$R_{\theta JA}$	77	104	$^{\circ}\text{C/W}$
	Steady State		103	130	
Junction-to-Lead Thermal Resistance	Steady State	$R_{\theta JL}$	51	65	

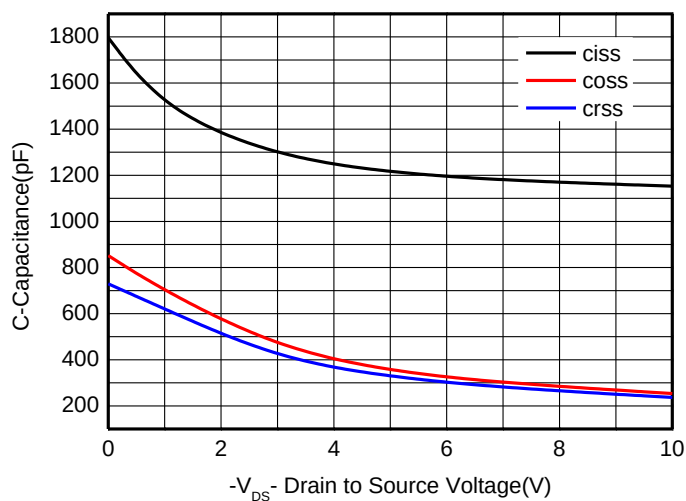
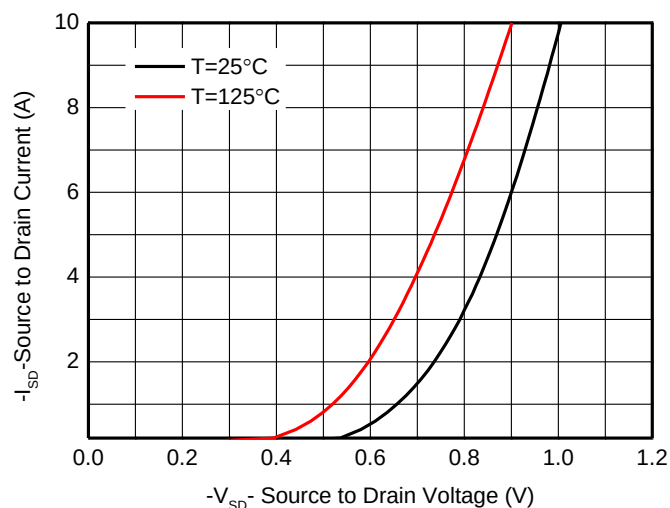
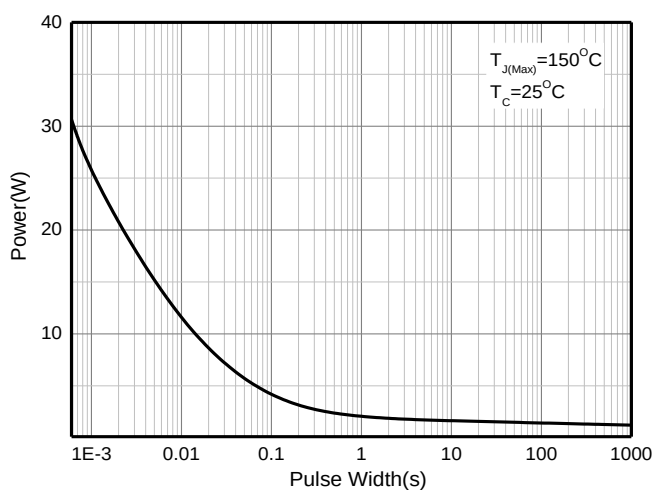
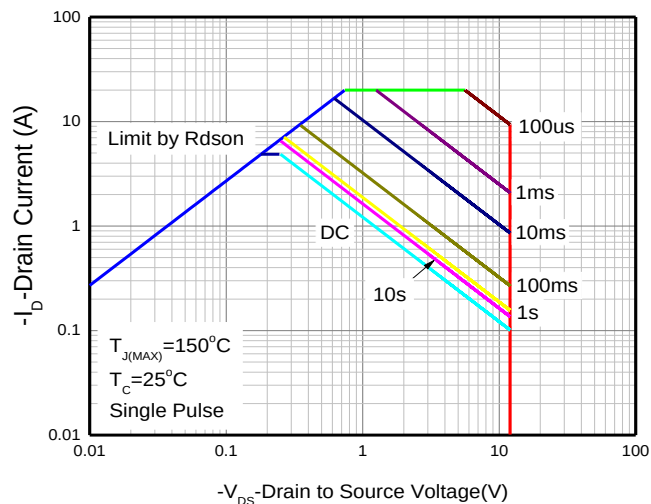
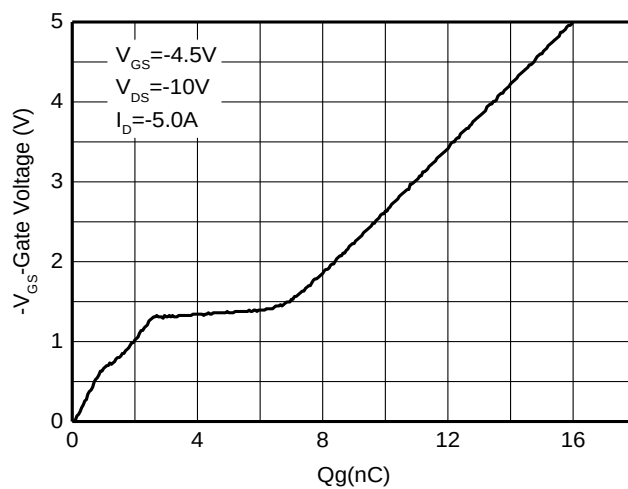
Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1-inch² (6.45cm²) with 2oz.(0.071mm thick) Copper pad on a 1.5*1.5 inch², 0.06-inch thick FR4 PCB, in a still air environment with $T_A = 25^{\circ}\text{C}$. The value in any given application is determined by the user's specific board design
- The power dissipation P_D is based on Junction-to-Ambient thermal resistance $R_{\theta JA}$ $t \leq 10\text{s}$ value and the $T_{J(\text{MAX})}=150^{\circ}\text{C}$.
- Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial $T_J = 25^{\circ}\text{C}$, the maximum allowed junction temperature of 150°C .
- The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

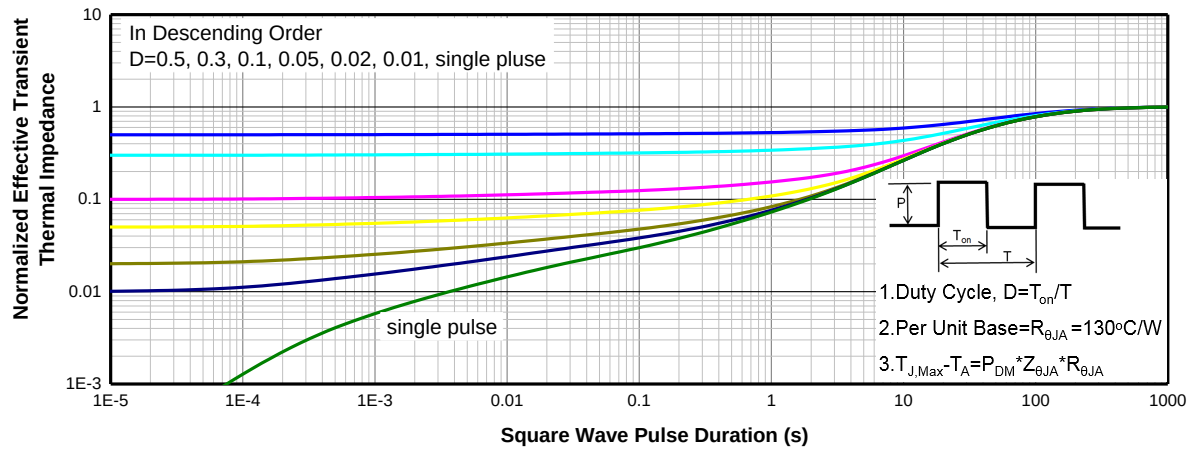
Electronics Characteristics (Ta=25°C, unless otherwise noted)

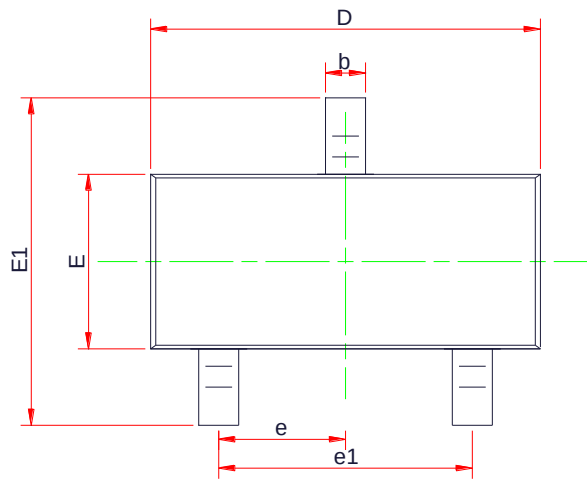
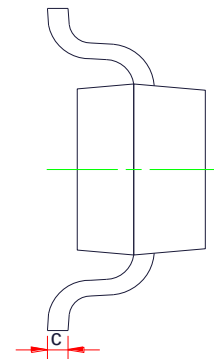
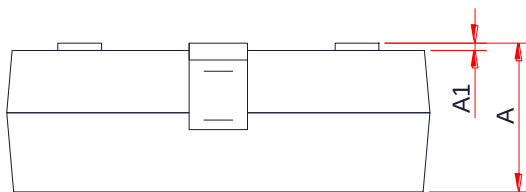
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0 V, I _D = -250uA	-12			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -10V, V _{GS} = 0V			-1	uA
Gate-to-source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8V			±1	uA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = -250uA	-0.45	-0.55	-0.85	V
Drain-to-source On-resistance ^{b, c}	R _{DS(on)}	V _{GS} = -4.5V, I _D = -5.0A		31	37	mΩ
		V _{GS} = -2.5V, I _D = -3.0A		40	55	
		V _{GS} = -1.8V, I _D = -2.0A		56	88	
Forward Trans conductance	g _{fs}	V _{DS} = -5.0V, I _D = -2.0A		8.5		S
CAPACITANCES, CHARGES						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = -10 V		1152		pF
Output Capacitance	C _{OSS}			253		
Reverse Transfer Capacitance	C _{RSS}			236		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = -4.5 V, V _{DD} = -10 V, I _D = -5.0A		14.6		nC
Threshold Gate Charge	Q _{G(TH)}			1.35		
Gate-to-Source Charge	Q _{GS}			2.3		
Gate-to-Drain Charge	Q _{GD}			5.7		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td(ON)	V _{GS} = -4.5 V, V _{DD} = -10 V, R _L =3 Ω, R _G =6 Ω		26		ns
Rise Time	tr			23		
Turn-Off Delay Time	td(OFF)			68		
Fall Time	tf			45		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = -1.0A		-0.8	-1.5	V

Typical Characteristics (Ta=25°C, unless otherwise noted)

Output characteristics

Transfer characteristics

On-Resistance vs. Drain current

On-Resistance vs. Gate-to-Source voltage

On-Resistance vs. Junction temperature

Threshold voltage vs. Temperature

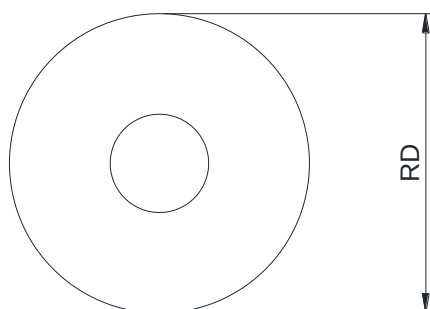
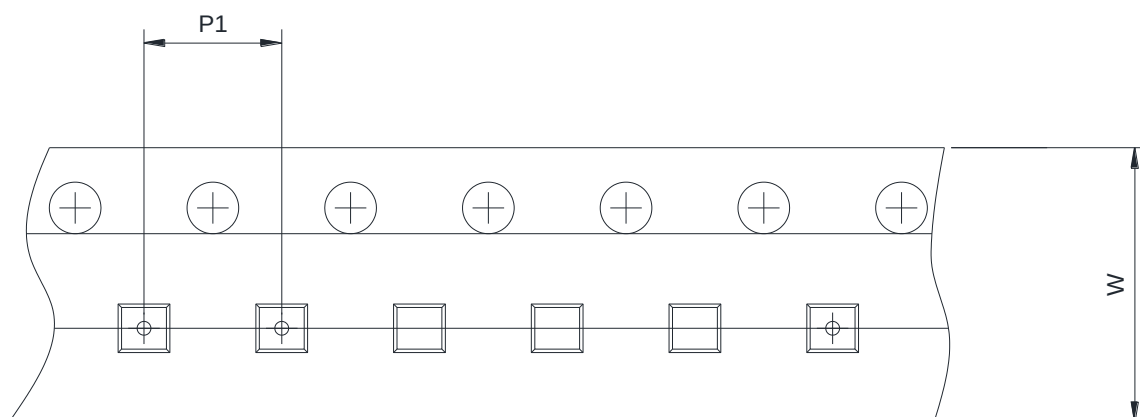
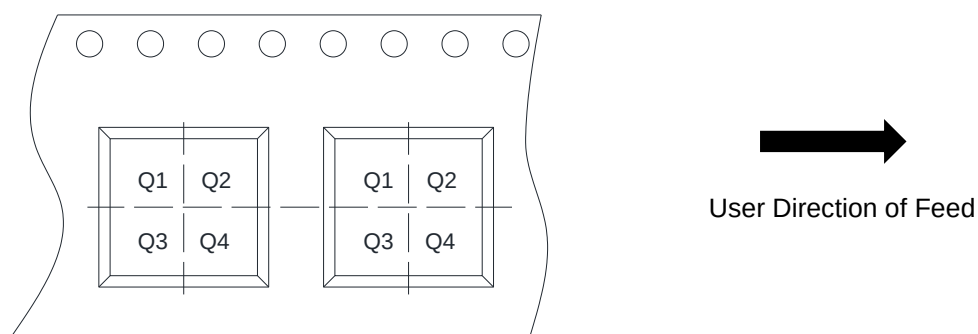

Capacitance

Body diode forward voltage

Single pulse power

Safe operating power

Gate charge Characteristics

Transient thermal response (Junction-to-Ambient)



Package Outline Dimensions
SOT-23

TOP VIEW

SIDE VIEW

SIDE VIEW

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.89	1.10	1.30
A1	0.00	-	0.10
b	0.30	0.43	0.55
c	0.05	-	0.20
D	2.70	2.90	3.10
E	1.15	1.33	1.50
E1	2.10	2.40	2.70
e	0.95 Typ.		
e1	1.70	1.90	2.10

TAPE AND REEL INFORMATION
Reel Dimensions

Tape Dimensions

Quadrant Assignments For PIN1 Orientation In Tape


RD	Reel Dimension	☒ 7inch	☐ 13inch
W	Overall width of the carrier tape	☒ 8mm	☐ 12mm ☐ 16mm
P1	Pitch between successive cavity centers	☐ 2mm	☒ 4mm ☐ 8mm
Pin1	Pin1 Quadrant	☐ Q1	☐ Q2 ☒ Q3 ☐ Q4